June 17, 2013

To: All customers using the CONSMA001-SMD-G and CONREVSMA001-SMD-G

Re: Product Change Notice

Dear customer,

Linx Technologies is announcing a change in manufacturing for the CONSMA001-SMD-G and CONREVSMA001-SMD-G.

The product is mechanically identical to, and offers equivalent electrical performance, as the previous version of the product. The manufacturing change made is the addition of four retention dimples equally spaced around each connector’s barrel to enhance insulation retention after connectors are subjected to solder reflow temperatures.

We are committed to working closely with our customers during the transition to address any questions or concerns.
Product Change Notice for CONSMA001-SMG-G and CONREVSMA001-SMD-G

PCN #: LPCN-130617-2
Publish Date: June 17, 2013

Type of Change
Manufacturing change for CONSMA001-SMD-G and CONREVSMA001-SMD-G

Products Affected
- CONSMA001-SMD-G
- CONREVSMA001-SMD-G

Description of Change
The addition of retention dimpling to the manufacturing process for the CONSMA001-SMD-G and CONREVSMA001-SMD-G has been implemented. The dimpling of the connectors is illustrated in Figure 2 below.

Figure 1: CONSMA001-SMD-G and CONREVSMA001-SMD-G without insulation retention dimples

Figure 2: CONSMA001-SMD-G and CONREVSMA001-SMD-G with insulation retention dimples
Reason for Change
To enhance retention of connector insulation after being subjected to solder reflow temperatures 260° Celsius.

Effect of Change
Form: Addition of retention dimples 90° apart on barrel of connectors
Fit: No change
Function: No change
Quality: No change

Anticipated First Ship Date
June 2013

Qualification Data
Qualification plan specifics are not for general release. Please contact Linx directly for additional information or assistance.

Last Time Buy Date
No formal last time buy date is established. Product with the additional retention dimpling will be supplied as existing inventory depletes.